

## ABSTRACT

Pads and methods of making the pads for applications such as polishing substrates  
5 and chemical mechanical planarization of substrates are provided. The pads are  
substantially porous and substantially hard for improved polishing and planarization  
properties. Pads according to some embodiments of the present invention have beneficial  
properties like those of standard technology porous pads and beneficial properties like those  
of standard technology hard pads.

10